

Product Change Notice (PCN)

Subject: Alternate Manufacturing Facility for Assembly of the Listed Intersil TQFP and LQFP Packaged Products

Publication Date: 4/7/2015

Effective Date: 7/6/2015

Revision Description:

Initial Release

Description of Change:

Alternate Manufacturing Facility for Assembly of the Listed Intersil TQFP and LQFP Packaged Products – Advanced Semiconductor Engineering (ASK) – Kaohsiung, Taiwan.

Reason for Change:

This notice is to inform you that Intersil will begin using Advanced Semiconductor Engineering (ASK) facility as an alternate manufacturing facility for assembly of the Listed Intersil TQFP (Thin Quad Flatpack) and LQFP (Low Quad Flatpack) packaged products. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. The Advanced Semiconductor Engineering (ASK) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified. ASK is qualified as a primary supplier to Intersil for high volume assembly of TQFP and LQFP packaged products.

Impact on fit, form, function, quality & reliability:

The assembly qualification plan is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the qualification result is included for reference. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, etc.) will continue to be processed to previously established conditions and systems

Product Identification:

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at ASK may also be identified by the assembly location code (country of assembly) when marked on the devices. Details of marking changes are illustrated in Appendix C.

Qualification status: Complete, see attached

Sample availability: 6/8/2015

Device material declaration: Available upon request

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.

For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: PCN-US@INTERSIL.COM	Europe: PCN-EU@INTERSIL.COM	Japan: PCN-JP@INTERSIL.COM	Asia Pac: PCN-APAC@INTERSIL.COM

Appendix A - Affected Products List (see attached)
 Appendix B - Qualification Results (see attached)
 Appendix C - Device marking (see attached)

Appendix A -

TW6805A-LA2-GR
 TW8807-LA2-GR
 TW8816-LA3-GRR5438
 TW8816-LA3-GRS
 TW8816-LA3-GRST
 TW8817-TA3-GRS
 TW8817-TA3-GRST
 TW8817-TA6-GRSHT
 TW8826-LA3-GR
 TW8827-TA3-GR

Appendix B -

Stress / Conditions	Duration	TW8834AT-TA2-GR	TW8836AT-LB2-GE
		100 Leads TQFP 12mm x 12mm	128 Leads LQFP 14mm x 14mm
Moisture Sensitivity Classification		N = 66 Acc = 0 L3 PB FREE	N = 22 Acc = 0 L3 PB FREE
Biased HAST +130°C / 85% RH	96 Hrs	N = 240 Acc = 0	N = 240 Acc = 0
Unbiased HAST +130°C / 85% RH	96 Hrs	N = 240 Acc = 0	N = 239 Acc = 0
High Temperature Storage TA = +150°C	500 Hrs	N = 50 Acc = 0	N = 50 Acc = 0
Temp Cycle +125°C / -50°C	1000 Cyc	N = 227 Acc = 0	N = 224 Acc = 0
High Temperature Operating Life (HTOL) TA = +125°C	408 Hrs	N=250 Acc = 0	N=160 Acc = 0
	1000 Hrs	N=80 Acc = 0	N=80 Acc = 0
Early Life Failure Rate TA = +125°C	24 Hrs	N = 2400 Acc = 0	N = 2400 Acc = 0

 Qualified by Extension (QBE)

Appendix C –

Device	Existing marking	New marking
TW6805A-LA2-GR		
Description of change	From	To
Top side marking	DCLA2-GR	DALA2-GR
Z = Assembly Location	A	Y
Country of Origin	China	Taiwan

Device	Existing marking	New marking
TW8807-LA2-GR		
Description of change	From	To
Top side marking	DELA2-GR	DALA2-GR
Z = Assembly Location	T	Y

Device	Existing marking	New marking
TW8816-LA3-GRR5438 TW8816-LA3-GRS TW8816-LA3-GRST		
Description of change	From	To
Top side marking	DELA3-GR	DALA3-GR
Z = Assembly Location	T	Y

Device	Existing marking	New marking
TW8817-TA3-GRS TW8817-TA3-GRST		
Description of change	From	To
Top side marking	DETA3-GR	DATA3-GR
Z = Assembly Location	T	Y

Device	Existing marking	New marking
TW8817-TA6-GRSHT		
Description of change	From	To
Top side marking	DETA6-GR	DATA6-GR
Z = Assembly Location	T	Y

Device	Existing marking	New marking
TW8826-LA3-GR		
Description of change	From	To
Top side marking	DELA3-GR	DALA3-GR
Z = Assembly Location	T	Y

Device	Existing marking	New marking
<p>TW8827-TA3-GR</p>	<p>Topside Marking</p> <p>Techwell TW8827 DETA3-GR ZYYWTTTT YYWW Country of Origin</p> <p>Pin 1 Part # Part # Con't. 4 Digit Date Code</p> <p>Pin 1 Bottom Marking ZYYWTTTT</p> <p>Z = Assembly Location Code per BRSP 427-001-1 YYWW = 4 Digit Date Code TTTT = Trace Code</p>	<p>Topside Marking</p> <p>Techwell TW8827 DATA3-GR ZYYWTTTT YYWW Country of Origin</p> <p>Pin 1 Part # Part # Con't. 4 Digit Date Code</p> <p>Pin 1 Bottom Marking ZYYWTTTT</p> <p>Z = Assembly Location Code per BRSP 427-001-1 YYWW = 4 Digit Date Code TTTT = Trace Code</p>
Description of change	From	To
Top side marking	DETA3-GR	DATA3-GR
Z = Assembly Location	T	Y